

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Huang et al.

Art Unit:

Application No.

CERTIFICATE OF MAILING

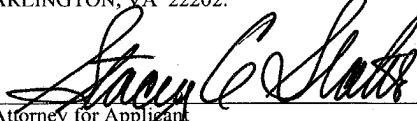
Filed: November 19, 2001

For: CHIP PACKAGE CAPABLE OF REDUCING
MOISTURE PENETRATION

Examiner:

I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service on November 20, 2001 as First Class Mail in an envelope addressed to: BOX FILING DATE, U.S. PATENT AND TRADEMARK OFFICE, ARLINGTON, VA 22202.

Date: November 20, 2001


Attorney for Applicant

COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

Petition to Accord Correspondence a Mailing Date

Sir:

Applicants hereby petition the U.S. Patent Office to accord the attached correspondence a mailing date of November 19, 2001. This correspondence was timely and correctly mailed on November 19, 2001, by express mail to file a continuation-in-part application. The continuation-in-part application should be accorded a filing date of November 19, 2001, and such action is respectfully requested.

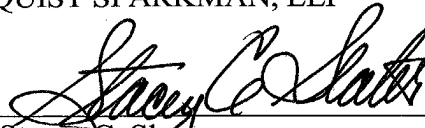
Applicants request that the Patent Office call the undersigned if there are any questions concerning this matter.

No fee should be required to file this petition. However, if the Patent Office determines that a fee is required, please deduct such fee from Deposit Account No. 02-4550.

*Receipt date
granted is
11/19/01.
J. Chang
from OPLA*

Respectfully submitted,
KLARQUIST SPARKMAN, LLP

By


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